

Vishay

vPolyTanTM Polymer Surface Mount Chip Capacitors, Low Profile, Leadframeless Molded Type



LINKS TO ADDITIONAL RESOURCES







PERFORMANCE / ELECTRICAL CHARACTERISTICS

Operating Temperature: -55 °C to +105 °C

Capacitance Range: 47 μF to 470 μF
Capacitance Tolerance: ± 20 %
Voltage Rating: 10 V_{DC} to 35 V_{DC}

FEATURES

- Ultra low ESR
- 100 % surge current tested
- · Accelerated voltage conditioning
- High ripple current capability
- Stable capacitance over operating temperature, voltage, and frequency range



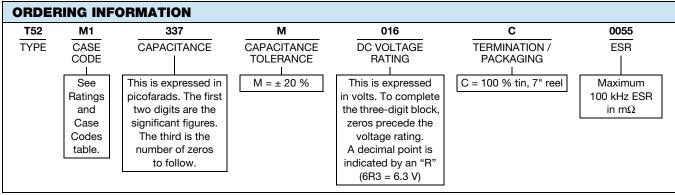
HALOGEN

FREE

- No wear out effect
- Molded case 7360, 7343, 3528 EIA size The molding compound has been selected to meet the requirements of UL 94 V-0 and outgassing requirements of ASTM E-595
- Lead (Pb)-free L-shaped face-down terminations
- 8 mm, 12 mm tape and reel packaging per EIA-481 standard
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

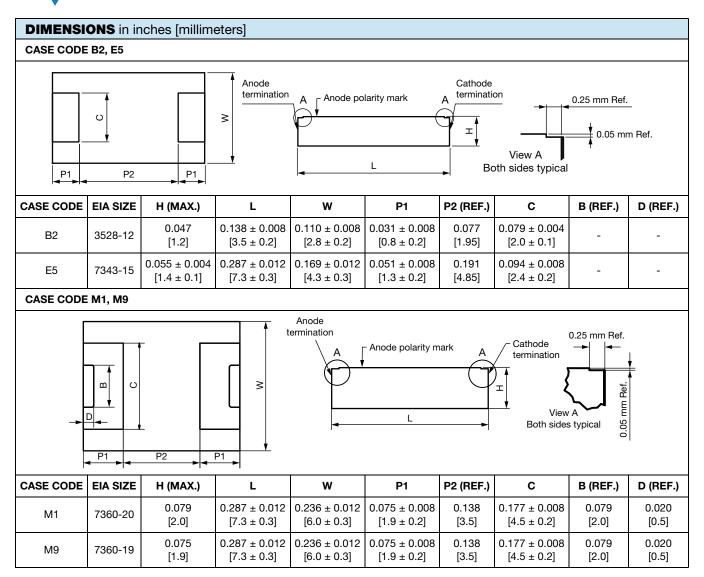
- · Decoupling, smoothing, filtering
- Bulk energy storage in Solid State Drives (SSD)
- Infrastructure equipment
- Storage and networking
- Computer motherboards
- · Smartphones and tablets



Notes

- We reserve the right to supply higher voltage ratings and tighter capacitance tolerance capacitors in the same case size.
 Voltage substitutions will be marked with the higher voltage rating
- We reserve the right to supply better series with more extensive screening

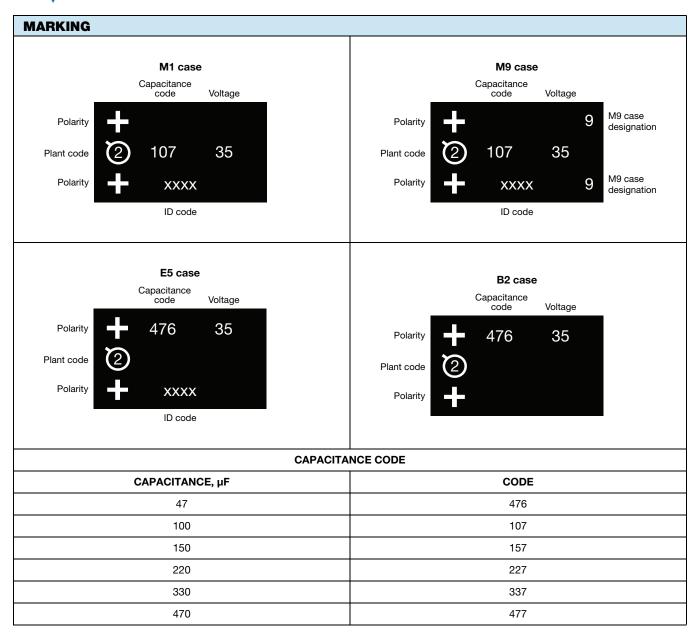
Revision: 05-Sep-2023



RATINGS AND CASE CODES (ESR m Ω)							
μF	10 V	16 V	20 V	25 V	35 V		
47		B2 (200)		E5 (55, 70, 100)	E5 (55, 70, 100)		
100			E5 (55, 70, 100)		M1 (55, 70, 100), M9 (55, 70 100)		
150		E5 (50, 70, 100)		M1 (55, 70, 100)			
220	M1 (55)	M1 (55, 70)		M1 (55, 70, 100)			
330	M1 (55)	M1 (40, 55)					
470		M1 (55) ⁽¹⁾					

⁽¹⁾ Rating in development, contact factory for availability

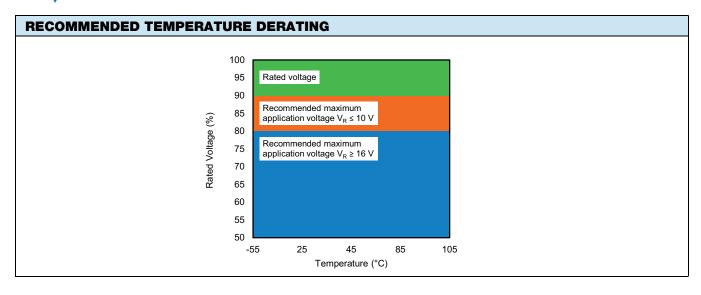
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STANDARI	, na i	INGS		144V DE	MAY 505	14 A V	HIGH TEMPERA	TUPE	
CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μA)	MAX. DF AT +25 °C 120 Hz (%)	MAX. ESR AT +25 °C 100 kHz	MAX. RIPPLE, 100 kHz I _{RMS}	LOAD TEMPERATURE	TIME	MSL
			10		(mΩ)	(A)	(°C)	(h)	
220	M1	T52M1227M010C0055	220	V _{DC} AT +105	55	2.828	105	2000	3
330	M1	T52M1337M010C0055	330	10	55 55	2.828	105	2000	3
330	IVI I	1321011337101010C0033		V _{DC} AT +105		2.020	103	2000	
47	B2	T52B2476M016C0200	75	10	200	0.612	85	2000	3
150	E5	T52E5157M016C0100	240	10	100	1.988	105	2000	3
150	E5	T52E5157M016C0070	240	10	70	2.375	105	2000	3
150	E5	T52E5157M016C0050	240	10	50	2.811	105	2000	3
220	M1	T52M1227M016C0070	352	10	70	2.510	105	2000	3
220	M1	T52M1227M016C0076	352	10	55	2.828	105	2000	3
330	M1	T52M1337M016C0055	528	10	55 55	2.828	105		3
								2000	
330	M1	T52M1337M016C0040	528	10	40	3.317	105	2000	3
470	M1 ⁽¹⁾	T52M1477M016C0055	752	10 V _{DC} AT +105	55 ° C	2.828	85	2000	3
100	E5	T52E5107M020C0100	200	10	100	1.988	105	2000	3
100			200	10	70		105		3
100	E5 E5	T52E5107M020C0070 T52E5107M020C0055	200	10	70 55	2.375 2.680	105	2000	3
100	EO	132E3107W020C0033		V _{DC} AT +105		2.000	105	2000	
47	E5	T52E5476M025C0100	118	10	100	1.988	105	2000	3
47	E5	T52E5476M025C0070	118	10	70	2.375	105	2000	3
47	E5	T52E5476M025C0076	118	10	55	2.680	105	2000	3
150	M1	T52M1157M025C0100	375	10	100	2.098	105	2000	3
150	M1	T52M1157M025C0070	375	10	70	2.510	105	2000	3
150	M1	T52M1157M025C0076	375	10	7 G 5 5	2.828	105	2000	3
220	M1	T52M1227M025C0100	550	10	100	2.028	85	2000	3
220		T52M1227M025C0100	550	10	70	2.510	85	2000	3
	M1 M1			10			85		3
220	IVI I	T52M1227M025C0055	550	V _{DC} AT +105	55 ° C	2.828	65	2000	<u> </u>
47	E 5	T52E5476M035C0100				1 000	105	2000	
47 47	E5 E5	T52E5476M035C0100	165 165	10 10	100 70	1.988 2.375	105 105	2000	3
47 47	E5	T52E5476M035C0070 T52E5476M035C0055	165 165	10	70 55	2.680	105	2000	3
		T52E5476M035C0055							3
100	M1		350	10	100	2.098	105	2000	3
100	M1	T52M1107M035C0070	350	10	70 55	2.510	105	2000	3
100	M1	T52M1107M035C0055	350	10	55	2.828	105	2000	3
100	M9	T52M9107M035C0100	350	10	100	2.098	105	2000	3
100	M9	T52M9107M035C0070	350	10	70	2.510	105	2000	3
100	M9	T52M9107M035C0055	350	10	55	2.828	105	2000	3

⁽¹⁾ Rating in development, contact factory for availability



RECOMMENDED VOLTAGE DERATING GUIDELINES							
CAPACITOR VOLTAGE RATING, V MAXIMUM OPERATING VOLTAGE, V							
6.3	5.7						
10	9.0						
16	12.8						
20	16						
25	20						
35	28						

POWER DISSIPATION	
CASE CODE	MAXIMUM PERMISSIBLE POWER DISSIPATION AT +45 °C WITH +30 °C RISE IN FREE AIR
B2	0.075
E5	0.395
M1, M9	0.44

STANDARD PACKAGING QUANTITY						
CASE CODE	UNITS PER 7" REEL					
B2	2500					
E5	1200					
M1, M9	1000					

ITEM	CONDITION	POST TEST PERFOR	MANCE
Life test at +85 °C	2000 h (according to Standard Ratings table)	Capacitance change	Within ± 20 % of initial value
or +105 °C ⁽¹⁾	application of rated voltage at 85 °C or 105 °C, MIL-STD-202 method 108	Dissipation factor	Within initial limits
	WILL OTD 202 Method 100	Leakage current	Shall not exceed 300 % of initial limit
Shelf life test	2000 h no voltage applied at 85 °C or 105 °C,	Capacitance change	Within ± 20 % of initial value
at +85 °C or +105 °C ⁽¹⁾	MIL-STD-202 method 108	Dissipation factor	Within initial limits
1100 0		Leakage current	Shall not exceed 300 % of initial limit
Humidity tests	At 60 °C / 90 % RH 500 h, no voltage applied	Capacitance change	-20 % to +40 % of initial value
		Dissipation factor	Within initial limit
		Leakage current	Shall not exceed 300 % of initial limit
Stability at low and	-55 °C	Capacitance change	Within -20 % to 0 % of initial value
high temperatures		Dissipation factor	Shall not exceed 150 % of initial limit
		Leakage current	n/a
	25 °C	Capacitance change	Within ± 20 % of initial value
		Dissipation factor	Within initial limit
		Leakage current	Within initial limit
	85 °C	Capacitance change	Within 0 % to +40 % of initial value
		Dissipation factor	Within initial limit
		Leakage current	Shall not exceed 1000 % of initial value
	105 °C	Capacitance change	Within 0 % to +40 % of initial value
		Dissipation factor	Within initial limits
		Leakage current	Shall not exceed 1000 % of initial limit
Surge voltage	85 °C, 1000 successive test cycles at 1.3 of	Capacitance change	Within ± 20 % of initial value
	rated voltage in series with a 33 Ω resistor at the rate of 30 s ON, 30 s OFF	Dissipation factor	Within initial limit
	110 1410 01 00 0 011, 00 0 011	Leakage current	Shall not exceed 300 % of initial limit
Temperature	1000 cycles (-55 °C to +125 °C)	Capacitance change	Within ± 20 % of initial value
cycling		Dissipation factor	Within initial limit
		Leakage current	Shall not exceed 300 % of initial limit
Shock	MIL-STD-202, method 213, condition E,	Capacitance change	Within ± 20 % of initial value
(specified pulse)	1000 g peak	Dissipation factor	Within initial limit
		Leakage current	Shall not exceed 300 % of initial limit
Vibration	MIL-STD-202, method 204, condition D, 10 Hz to 2000 Hz 20 <i>g</i> peak	There shall be no med post-conditioning.	hanical or visual damage to capacitors
Shear test	Apply a pressure load of 17.7 N for 10 s ± 1 s	Capacitance change	Within ± 20 % of initial value
	horizontally to the center of capacitor side body	Dissipation factor	Within initial limit
		Leakage current	Shall not exceed 300 % of initial limit

⁽¹⁾ Temperature according to Standard Ratings table

PRODUCT INFORMATION	
Polymer Guide	www.vishay.com/doc?40076
Moisture Sensitivity	www.vishay.com/doc?40135
Infographic	www.vishay.com/doc?48084
Sample Board	www.vishay.com/doc?48073
FAQ	
Frequently Asked Questions	www.vishay.com/doc?42106



Guide for Tantalum Solid Electrolyte Chip Capacitors With Polymer Cathode

INTRODUCTION

Tantalum electrolytic capacitors are the preferred choice in applications where volumetric efficiency, stable electrical parameters, high reliability, and long service life are primary considerations. The stability and resistance to elevated temperatures of the tantalum/tantalum oxide/manganese dioxide system make solid tantalum capacitors an appropriate choice for today's surface mount assembly technology.

Vishay Sprague has been a pioneer and leader in this field, producing a large variety of tantalum capacitor types for consumer, industrial, automotive, military, and aerospace electronic applications.

Tantalum is not found in its pure state. Rather, it is commonly found in a number of oxide minerals, often in combination with Columbium ore. This combination is known as "tantalite" when its contents are more than one-half tantalum. Important sources of tantalite include Australia, Brazil, Canada, China, and several African countries. Synthetic tantalite concentrates produced from tin slags in Thailand, Malaysia, and Brazil are also a significant raw material for tantalum production.

Electronic applications, and particularly capacitors, consume the largest share of world tantalum production. Other important applications for tantalum include cutting tools (tantalum carbide), high temperature super alloys, chemical processing equipment, medical implants, and military ordnance.

Vishay Sprague is a major user of tantalum materials in the form of powder and wire for capacitor elements and rod and sheet for high temperature vacuum processing.

THE BASICS OF TANTALUM CAPACITORS

Most metals form crystalline oxides which are non-protecting, such as rust on iron or black oxide on copper. A few metals form dense, stable, tightly adhering, electrically insulating oxides. These are the so-called "valve" metals and include titanium, zirconium, niobium, tantalum, hafnium, and aluminum. Only a few of these permit the accurate control of oxide thickness by electrochemical means. Of these, the most valuable for the electronics industry are aluminum and tantalum.

Capacitors are basic to all kinds of electrical equipment, from radios and television sets to missile controls and automobile ignitions. Their function is to store an electrical charge for later use.

Capacitors consist of two conducting surfaces, usually metal plates, whose function is to conduct electricity. They are separated by an insulating material or dielectric. The dielectric used in all tantalum electrolytic capacitors is tantalum pentoxide.

Tantalum pentoxide compound possesses high-dielectric strength and a high-dielectric constant. As capacitors are being manufactured, a film of tantalum pentoxide is applied to their electrodes by means of an electrolytic process. The film is applied in various thicknesses and at various voltages and although transparent to begin with, it takes on different colors as light refracts through it. This coloring occurs on the tantalum electrodes of all types of tantalum capacitors.

Rating for rating, tantalum capacitors tend to have as much as three times better capacitance/volume efficiency than aluminum electrolytic capacitors. An approximation of the capacitance/volume efficiency of other types of capacitors may be inferred from the following table, which shows the dielectric constant ranges of the various materials used in each type. Note that tantalum pentoxide has a dielectric constant of 26, some three times greater than that of aluminum oxide. This, in addition to the fact that extremely thin films can be deposited during the electrolytic process mentioned earlier, makes the tantalum capacitor extremely efficient with respect to the number of microfarads available per unit volume. The capacitance of any capacitor is determined by the surface area of the two conducting plates, the distance between the plates, and the dielectric constant of the insulating material between the plates.

COMPARISON OF CAPACITOR DIELECTRIC CONSTANTS						
DIELECTRIC	e DIELECTRIC CONSTANT					
Air or vacuum	1.0					
Paper	2.0 to 6.0					
Plastic	2.1 to 6.0					
Mineral oil	2.2 to 2.3					
Silicone oil	2.7 to 2.8					
Quartz	3.8 to 4.4					
Glass	4.8 to 8.0					
Porcelain	5.1 to 5.9					
Mica	5.4 to 8.7					
Aluminum oxide	8.4					
Tantalum pentoxide	26					
Ceramic	12 to 400K					

In the tantalum electrolytic capacitor, the distance between the plates is very small since it is only the thickness of the tantalum pentoxide film. As the dielectric constant of the tantalum pentoxide is high, the capacitance of a tantalum capacitor is high if the area of the plates is large:

$$C = \frac{eA}{t}$$

where

C = capacitance

e = dielectric constant

A = surface area of the dielectric

t = thickness of the dielectric

Tantalum capacitors contain either liquid or solid electrolytes. In solid electrolyte capacitors, a dry material (manganese dioxide) forms the cathode plate. A tantalum lead is embedded in or welded to the pellet, which is in turn connected to a termination or lead wire. The drawings show the construction details of the surface mount types of tantalum capacitors shown in this catalog.

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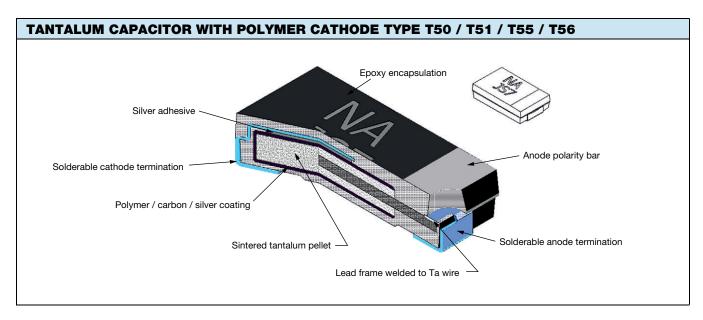


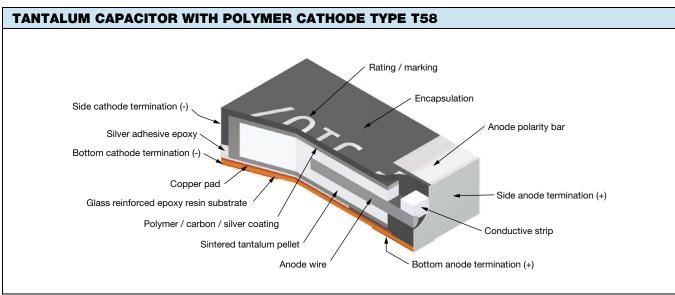
SOLID ELECTROLYTE POLYMER TANTALUM CAPACITORS

Solid electrolyte polymer capacitors utilize sintered tantalum pellets as anodes. Tantalum pentoxide dielectric layer is formed on the entire surface of anode, which is further impregnated with highly conductive polymer as cathode system.

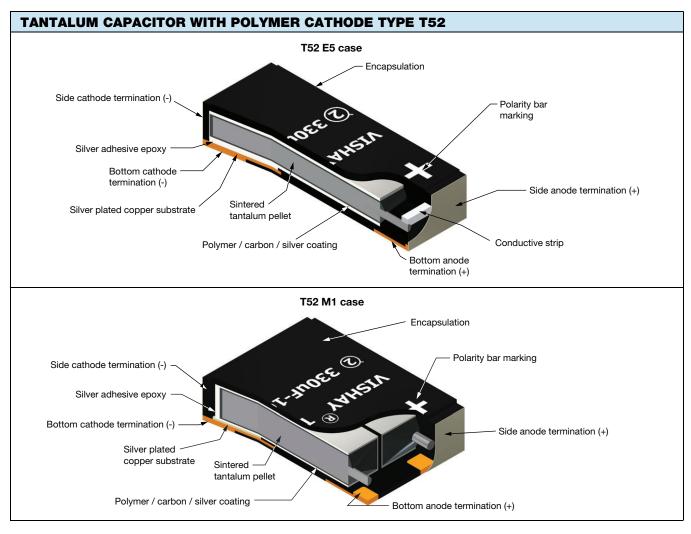
The conductive polymer layer is then coated with graphite, followed by a layer of metallic silver, which provides a conductive surface between the capacitor element and the outer termination (lead frame or other).

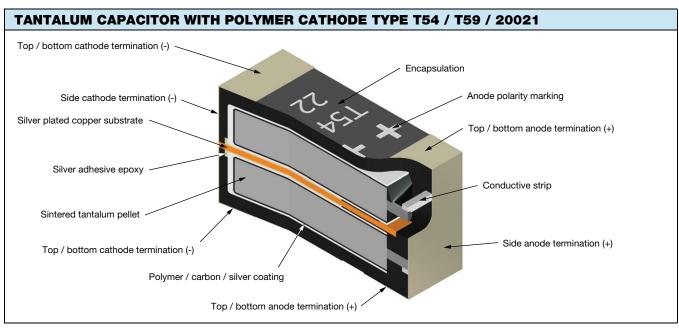
Molded chip polymer tantalum capacitor encases the element in plastic resins, such as epoxy materials. The molding compound has been selected to meet the requirements of UL 94 V-0 and outgassing requirements of ASTM E-595. After assembly, the capacitors are tested and inspected to assure long life and reliability. It offers excellent reliability and high stability for variety of applications in electronic devices. Usage of conductive polymer cathode system provides very low equivalent series resistance (ESR), which makes the capacitors particularly suitable for high frequency applications.



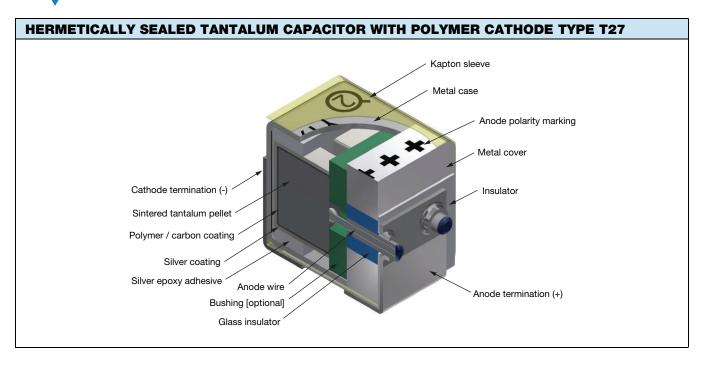












POLYMER CAPACITORS - METAL CASE, HERMETICALLY SEALED						
SERIES	T27					
PRODUCT IMAGE						
TYPE	VPolyTan TM hermetically sealed polymer surface-mount chip capacitors, low ESR					
FEATURES	Hermetically sealed in metal case, low ESR / low DCL, hi-rel. processing					
TEMPERATURE RANGE	-55 °C to +125 °C					
CAPACITANCE RANGE	15 μF to 470 μF					
VOLTAGE RANGE	16 V to 75 V					
CAPACITANCE TOLERANCE	± 20 %					
LEAKAGE CURRENT	0.05 CV					
DISSIPATION FACTOR	12 %					
ESR	25 m Ω to 100 m Ω					
CASE SIZES	D					
TERMINATION FINISH	100 % tin; tin / lead					

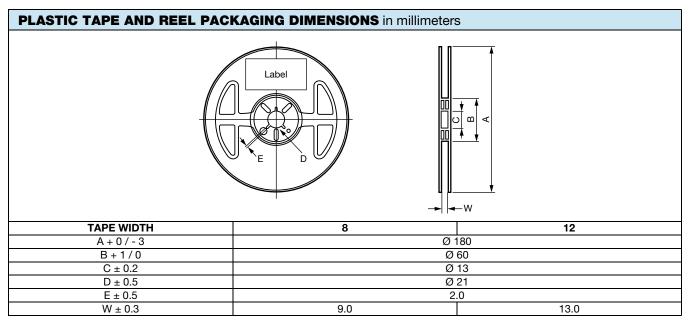


POLYMER CAPACITORS - MOLDED CASE						
SERIES	T50, T51, T55, T56					
PRODUCT IMAGE	THE REAL PROPERTY OF THE PERSON OF THE PERSO					
TYPE	VPolyTan TM , molded case, high performance polymer					
FEATURES	High performance					
TEMPERATURE RANGE	-55 °C to +105 °C / +125 °C					
CAPACITANCE RANGE	3.3 μF to 1000 μF					
VOLTAGE RANGE	2.5 V to 63 V					
CAPACITANCE TOLERANCE	± 20 %					
LEAKAGE CURRENT	0.1 CV					
DISSIPATION FACTOR	8 % to 10 %					
ESR	6 m Ω to 500 m Ω					
CASE SIZES	J, P, A, T, B, Z, V, D, C					
TERMINATION FINISH	Cases J, P, C: 100 % tin Case A, T, B, Z, V, D: Ni / Pd / Au					

POLYMER C	POLYMER CAPACITORS - LEADFRAMELESS MOLDED CASE								
SERIES	T52	T58	T59	T54	20021				
PRODUCT IMAGE		E 1/07							
ТҮРЕ	vPolyTan TM polymer surface mount chip capacitors, low profile, leadframeless molded type	vPolyTan TM polymer surface mount chip capacitors, compact, leadframeless molded type	vPolyTan TM polymer surface mount chip capacitors, low ESR, leadframeless molded type	vPolyTan TM polymer surface mount chip capacitors, low ESR, leadframeless molded type, hi-rel commercial off-the-shelf (COTS)	vPolyTan TM polymer surface mount chip capacitors, low ESR, leadframeless molded type, DLA approved				
FEATURES	Low profile	Small case size	Multianode	Hi-rel COTS, multianode	Multianode				
TEMPERATURE RANGE	-55 °C to +105 °C	-55 °C to +105 °C	-55 °C to +105 °C	-55 °C to +125 °C	-55 °C to +125 °C				
CAPACITANCE RANGE	47 μF to 1500 μF	1 μF to 330 μF	15 μF to 470 μF	15 μF to 470 μF (discrete capacitors) 30 μF to 2800 μF (stacked capacitors)	15 μF to 470 μF				
VOLTAGE RANGE	10 V to 35 V	6.3 V to 35 V	16 V to 75 V	16 V to 75 V	16 V to 63 V				
CAPACITANCE TOLERANCE	± 20 %	± 20 %	± 10 %, ± 20 %	± 20 %	± 20 %				
LEAKAGE CURRENT			0.1 CV						
DISSIPATION FACTOR	10 %	8 % to 14 %	12 %	12 %	10 %				
ESR	25 m Ω to 55 m Ω	50 m Ω to 500 m Ω	25 m Ω to 150 m Ω	5 m Ω to 150 m Ω	25 m Ω to 150 m Ω				
CASE SIZES	E5, M1, M9, B2	MM, W0, W9, A0, BB	EE	EE, E2, E3, E4, E6	EE				
TERMINATION	100	% tin	100 % tin	; tin / lead	Tin / lead				

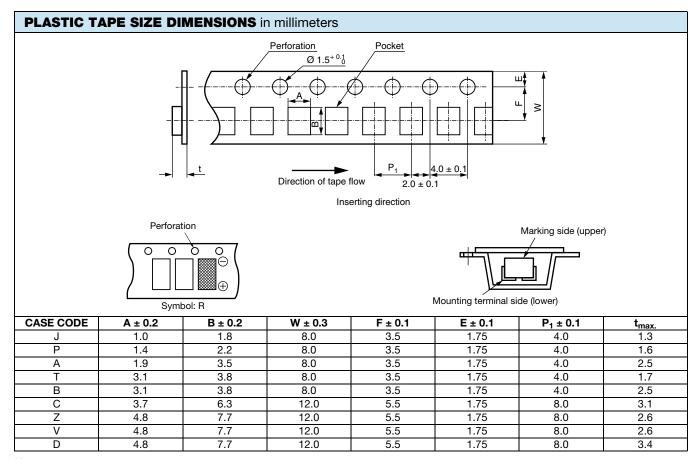


MOLDED CAPACITORS, T50 / T51 / T55 / T56 TYPES



Note

· A reel diameter of 330 mm is also applicable



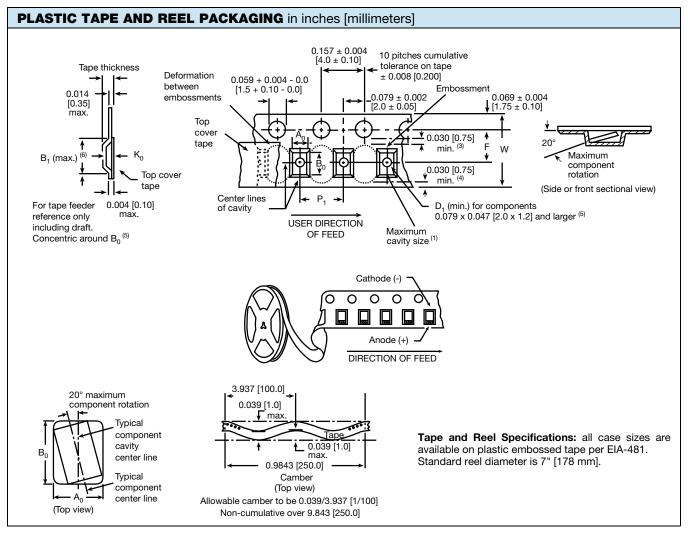
Note

A reel diameter of 330 mm is also applicable

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LEADFRAMELESS MOLDED CAPACITORS, ALL TYPES



Notes

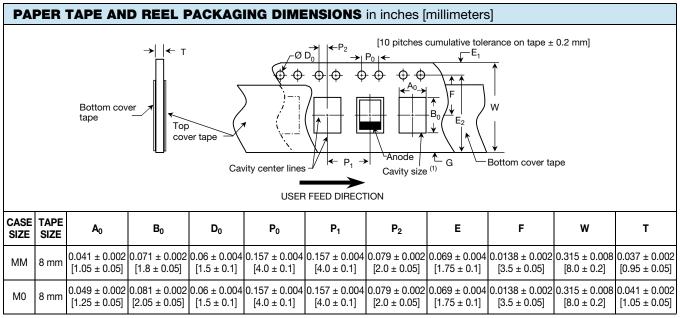
- Metric dimensions will govern. Dimensions in inches are rounded and for reference only
- (1) A₀, B₀, K₀, are determined by the maximum dimensions to the ends of the terminals extending from the component body and / or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A₀, B₀, K₀) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°
- (2) Tape with components shall pass around radius "R" without damage. The minimum trailer length may require additional length to provide "R" minimum for 12 mm embossed tape for reels with hub diameters approaching N minimum
- (3) This dimension is the flat area from the edge of the sprocket hole to either outward deformation of the carrier tape between the embossed cavities or to the edge of the cavity whichever is less
- (4) This dimension is the flat area from the edge of the carrier tape opposite the sprocket holes to either the outward deformation of the carrier tape between the embossed cavity or to the edge of the cavity whichever is less
- (5) The embossed hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location shall be applied independent of each other
- (6) B₁ dimension is a reference dimension tape feeder clearance only



CARRIER	CARRIER TAPE DIMENSIONS in inches [millimeters]							
CASE CODE	TAPE SIZE	B ₁ (MAX.) ⁽¹⁾	D ₁ (MIN.)	F	K ₀ (MAX.)	P ₁	P ₂	w
E5	12 mm	0.329 [8.35]	0.059 [1.5]	0.217 ± 0.002 [5.50 ± 0.05]	0.071 [1.8]	0.315 ± 0.004 [8.0 ± 0.10]	0.079 ± 0.002 [2.00 ± 0.05]	0.476 ± 0.008 [12.1 ± 0.20]
MM ⁽²⁾	8 mm	0.075 [1.91]	0.02 [0.5]	0.138 [3.5]	0.043 [1.10]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
M1, M9	12 mm	0.32 [8.2]	0.059 [1.5]	0.217 ± 0.002 [5.5 ± 0.05]	0.094 [2.39]	0.315 ± 0.04 [8.0 ± 1.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.472 + 0.012 / - 0.004 [12.0 + 0.3 / - 0.10]
W9	8 mm	0.126 [3.20]	0.030 [0.75]	0.138 [3.5]	0.045 [1.15]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
WO	8 mm	0.126 [3.20]	0.030 [0.75]	0.138 [3.5]	0.045 [1.15]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
A0	8 mm	1	0.02 [0.5]	0.138 [3.5]	0.049 [1.25]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
ВВ	8 mm	0.157 [4.0]	0.039 [1.0]	0.138 [3.5]	0.087 [2.22]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
EE	12 mm	0.32 [8.2]	0.059 [1.5]	0.217 ± 0.002 [5.5 ± 0.05]	0.175 [4.44]	0.315 ± 0.04 [8.0 ±1.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.472 + 0.012 / - 0.004 [12.0 + 0.3 / - 0.10]
B2	8 mm	0.157 [4.0]	0.039 [1.0]	0.138 [3.5]	0.057 [1.45]	0.157 [4.0]	0.079 ± 0.002 [2.00 ± 0.05]	0.315 [8.0]
D (3)	16 mm	0.321 [8.16]	0.059 [1.5]	0.295 ± 0.004 [7.50 ± 0.1]	0.308 [7.83]	0.472 ± 0.004 [12.00 ± 0.1]	0.079 ± 0.004 $[2.00 \pm 0.1]$	0.630 ± 0.012 [16.00 ± 0.3]

Notes

- (1) For reference only
- (2) Standard packaging of MM case is with paper tape. Plastic tape is available per request
- (3) Tape thickness 0.018 [0.45] max.



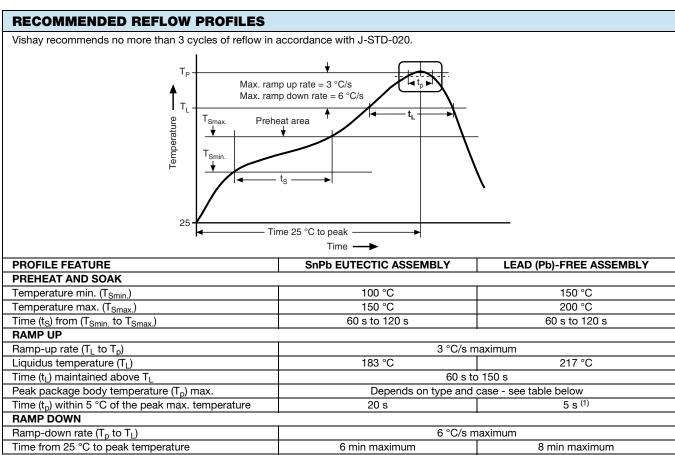
⁽¹⁾ A₀, B₀ are determined by the maximum dimensions to the ends of the terminals extending from the component body and / or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A₀, B₀) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°



PACKING AND STORAGE

Polymer capacitors meet moisture sensitivity level rating (MSL) of 3 or 4 as specified in IPC/JEDEC® J-STD-020 and are dry packaged in moisture barrier bags (MBB) per J-STD-033. MSL for each particular family is defined in the datasheet - either in "Features" section or "Standard Ratings" table. Level 3 specifies a floor life (out of bag) of 168 hours and level 4 specifies a floor life of 72 hours at 30 °C maximum and 60 % relative humidity (RH). Unused capacitors should be re-sealed in the MBB with fresh desiccant. A moisture strip (humidity indicator card) is included in the bag to assure dryness. To remove excess moisture, capacitors can be dried at 40 °C (standard "dry box" conditions).

For detailed recommendations please refer to J-STD-033.



Note

(1) For T27, lead (Pb)-free capacitors $t_p = 30 \text{ s}$

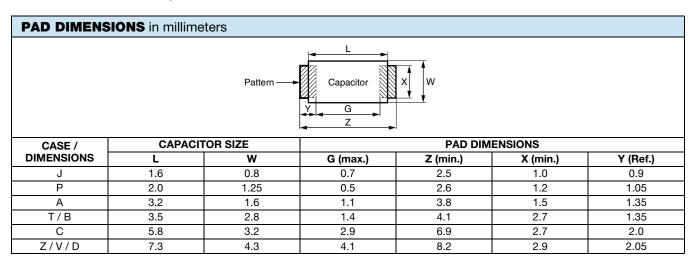
PEAK PACKAGE BODY TEMPERATURE (Tp) MAXIMUM				
TYPE	CASE CODE	PEAK PACKAGE BODY TEMPERATURE (T _P) MAX.		
		SnPb EUTECTIC ASSEMBLY	LEAD (Pb)-FREE ASSEMBLY	
T27	D	220 °C	245 °C	
T55	J, P, A, T, B, C, Z, V, D	n/a 260 °C 260 °C 260 °C 260 °C 260 °C 260 °C 250 °C	260 °C	
T52	E5, M1, M9, B2		260 °C	
T58	MM, W9, W0, A0, BB		260 °C	
T50	D		260 °C	
T51	D, V		260 °C	
T56	B, D, V		250 °C	
T59	EE	220 °C	250 °C	
T54	3E, 6E, EE, E2, E3, E4, E6	220 °C	250 °C	
20021	EE	220 °C	n/a	

Notes

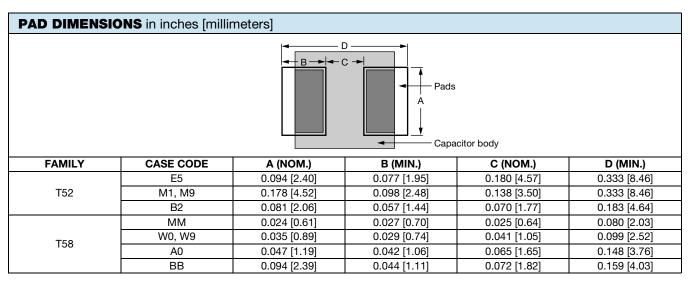
- T50, T51, T52, T55, T56, and T58 capacitors are process sensitive. PSL classification to JEDEC J-STD-075: R4G
- T54 and T59 capacitors with 100 % tin termination are process sensitive. PSL classification to JEDEC J-STD-075: R6G



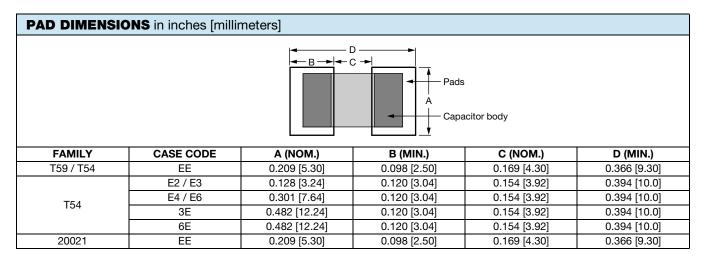
MOLDED CAPACITORS, T50 / T51 / T55 / T56 TYPES



LEADFRAMELESS MOLDED CAPACITORS T52 / T58

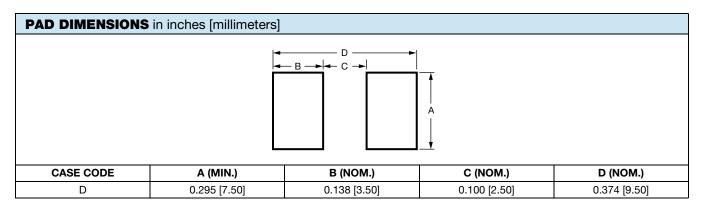


LEADFRAMELESS MOLDED CAPACITORS T59 / T54 / 20021



Revision: 08-Sep-2022 10 Document Number: 40076

HERMETICALLY SEALED CAPACITOR T27 TYPE



GUIDE TO APPLICATION

 AC Ripple Current: the maximum allowable ripple current shall be determined from the formula:

$$I_{RMS} = \sqrt{\frac{P}{R_{ESR}}}$$

where,

P = power dissipation in W at +45 °C as given in the tables in the product datasheets.

R_{ESR} = the capacitor equivalent series resistance at the specified frequency.

 AC Ripple Voltage: the maximum allowable ripple voltage shall be determined from the formula:

$$V_{RMS} = Z \sqrt{\frac{P}{R_{ESR}}}$$

or, from the formula:

$$V_{RMS} = I_{RMS} \times Z$$

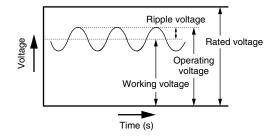
where,

P = power dissipation in W at +45 °C as given in the tables in the product datasheets.

R_{ESR} = The capacitor equivalent series resistance at the specified frequency.

Z = The capacitor impedance at the specified frequency.

2.1 The tantalum capacitors must be used in such a condition that the sum of the working voltage and ripple voltage peak values does not exceed the rated voltage as shown in figure below.



3. **Temperature Derating:** power dissipation is affected by the heat sinking capability of the mounting surface. If these capacitors are to be operated at temperatures above +45 °C, the permissible ripple current (or voltage) shall be calculated using the derating coefficient as shown in the table below:

MAXIMUM RIPPLE CURRENT TEMPERATURE DERATING FACTOR		
≤ 45 °C	1.0	
55 °C	0.8	
85 °C	0.6	
105 °C	0.4	
125 °C	0.25	

 Reverse Voltage: the capacitors are not intended for use with reverse voltage applied. However, they are capable of withstanding momentary reverse voltage peaks, which must not exceed the following values:

At 25 $^{\circ}\text{C}$: 10 % of the rated voltage or 1 V, whichever is smaller.

At 85 $^{\circ}\text{C}$: 5 % of the rated voltage or 0.5 V, whichever is smaller.

At 105 °C: 3 % of the rated voltage or 0.3 V, whichever is smaller.

5. Mounting Precautions:

5.1 **Soldering:** capacitors can be attached by conventional soldering techniques; vapor phase, convection reflow, infrared reflow, wave soldering, and hot plate methods. The soldering profile charts show recommended time / temperature conditions for soldering. Preheating is recommended. The recommended maximum ramp rate is 3 °C per second. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor. For details see www.vishay.com/doc?40214.



Limit Pressure on Capacitor Installation with 5.2 Mounter: pressure must not exceed 4.9 N with a tool end diameter of 1.5 mm when applied to the capacitors using an absorber, centering tweezers, or similar (maximum permitted pressurization time: 5 s). An excessively low absorber setting position would result in not only the application of undue force to the capacitors but capacitor and other component scattering, circuit board wiring breakage, and / or cracking as well, particularly when the capacitors are mounted together with other chips having a height of 1 mm or less.

www.vishay.com

5.3 Flux Selection

- 5.3.1 Select a flux that contains a minimum of chlorine and amine.
- 5.3.2 After flux use, the chlorine and amine in the flux remain must be removed.
- 5.4 Cleaning After Mounting: the following solvents are usable when cleaning the capacitors after mounting. Never use a highly active solvent.
 - Halogen organic solvent (HCFC225, etc.)
 - Alcoholic solvent (IPA, ethanol, etc.)
 - · Petroleum solvent, alkali saponifying agent, water, etc.

Circuit board cleaning must be conducted at a temperature of not higher than 50 °C and for an immersion time of not longer than 30 minutes. When an ultrasonic cleaning method is used, cleaning must be conducted at a frequency of 48 kHz or lower, at an vibrator output of 0.02 W/cm³, at a temperature of not higher than 40 °C, and for a time of 5 minutes or shorter.

- · Care must be exercised in cleaning process so that the mounted capacitor will not come into contact with any cleaned object or the like or will not get rubbed by a stiff brush or similar. If such precautions are not taken particularly when the ultrasonic cleaning method is employed, terminal breakage may occur
- When performing ultrasonic cleaning under conditions other than stated above, conduct adequate advance checkout

Legal Disclaimer Notice



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